

# Operational Amplifier, Precision, Zero-Drift, 50 $\mu\text{V}$ Offset, 0.25 $\mu\text{V}/^\circ\text{C}$ , 35 $\mu\text{A}$

## NCS325, NCS2325, NCS4325

The NCS325, NCS2325 and NCS4325 are CMOS operational amplifiers providing precision performance. The Zero-Drift architecture allows for continuous auto-calibration, which provides very low offset, near-zero drift over time and temperature, and near flat 1/f noise at only 35  $\mu\text{A}$  (max) quiescent current. These benefits make these devices ideal for precision DC applications. These op amps provide rail-to-rail input and output performance and are optimized for low voltage operation as low as 1.8 V and up to 5.5 V. The single channel NCS325 is available in the space-saving SOT23-5 package. The dual channel NCS2325 is available in Micro8 and SOIC-8. The quad channel NCS4325 is available in SOIC-14.

### Features

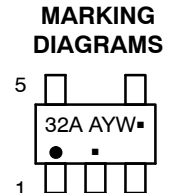
- Low Offset Voltage: 14  $\mu\text{V}$  typ, 50  $\mu\text{V}$  max at 25°C for NCS325
- Zero Drift: 0.25  $\mu\text{V}/^\circ\text{C}$  max
- Low Noise: 1  $\mu\text{Vpp}$ , 0.1 Hz to 10 Hz
- Quiescent Current: 21  $\mu\text{A}$  typ, 35  $\mu\text{A}$  max at 25°C
- Supply Voltage: 1.8 V to 5.5 V
- Rail-to-Rail Input and Output
- Internal EMI Filtering
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Typical Applications

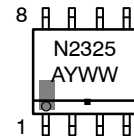
- Battery Powered Instruments
- Temperature Measurements
- Transducer Applications
- Electronic Scales
- Medical Instrumentation
- Current Sensing



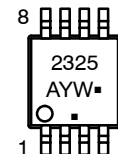
TSOP-5  
(SOT23-5)  
SN SUFFIX  
CASE 483



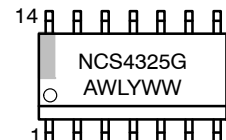
SOIC-8  
D SUFFIX  
CASE 751



MSOP-8  
DM SUFFIX  
CASE 846A



SOIC-14  
D SUFFIX  
CASE 751A



A = Assembly Location  
Y = Year  
WL = Wafer Lot  
W or WW = Work Week  
G or ■ = Pb-Free Package

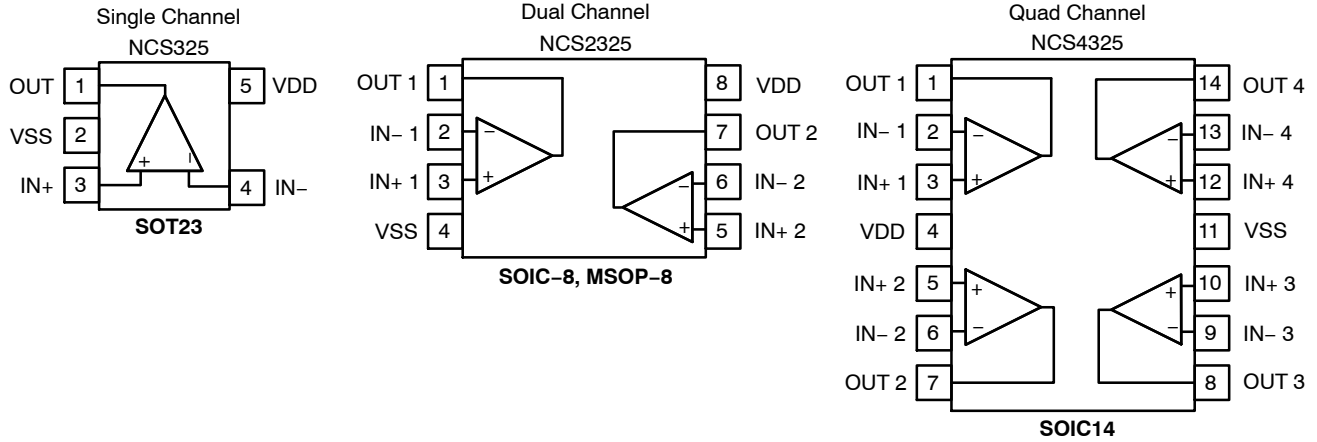
(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# NCS325, NCS2325, NCS4325

## PIN CONNECTIONS



## ORDERING INFORMATION

Configuration	Device	Package	Shipping <sup>†</sup>
Single	NCS325SN2T1G	SOT23-5 / TSOP-5	3000 / Tape & Reel
Dual	NCS2325DR2G	SOIC-8	3000 / Tape & Reel
	NCS2325DMR2G	Micro8 / MSOP-8	4000 / Tape & Reel
Quad	NCS4325DR2G	SOIC-14	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

# NCS325, NCS2325, NCS4325

**ABSOLUTE MAXIMUM RATINGS** Over operating free-air temperature, unless otherwise stated.

Parameter	Rating	Unit
Supply Voltage	6	V

## INPUT AND OUTPUT PINS

Input Voltage (Note 1)	$(V_{SS}) - 0.3$ to $(V_{DD}) + 0.3$	V
Input Current (Note 1)	$\pm 10$	mA
Output Short Circuit Current (Note 2)	Continuous	

## TEMPERATURE

Operating Temperature	-40 to +150	°C
Storage Temperature	-65 to +150	°C
Junction Temperature	+150	°C

## ESD RATINGS (Note 3)

Human Body Model (HBM)	4000	V
Machine Model (MM)	200	V

## OTHER RATINGS

Latch-up Current (Note 4)	100	mA
MSL	Level 1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3 V beyond the supply rails should be current limited to 10 mA or less
2. Short-circuit to ground.
3. This device series incorporates ESD protection and is tested by the following methods:  
ESD Human Body Model tested per AEC-Q100-002 (JEDEC standard: JESD22-A114)  
ESD Machine Model tested per AEC-Q100-003 (JEDEC standard: JESD22-A115)
4. Latch-up Current tested per JEDEC standard: JESD78.

## THERMAL INFORMATION

Thermal Metric	Symbol	Package	Value	Unit
Junction to Ambient (Note 5)	$\theta_{JA}$	SOT23-5 / TSOP-5	235	°C/W
		Micro8 / MSOP-8	298	
		SOIC-8	250	
		SOIC-14	216	

5. As mounted on an 80x80x1.5 mm FR4 PCB with 650 mm<sup>2</sup> and 2 oz (0.034 mm) thick copper heat spreader. Following JEDEC JESD/EIA 51.1, 51.2, 51.3 test guidelines

## OPERATING CONDITIONS

Parameter	Symbol	Range	Unit
Supply Voltage ( $V_{DD} - V_{SS}$ )	$V_S$	1.8 to 5.5	V
Specified Operating Range	$T_A$	-40 to 125	°C
Input Common Mode Voltage Range	$V_{ICMR}$	$V_{SS}-0.1$ to $V_{DD}+0.1$	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# NCS325, NCS2325, NCS4325

## ELECTRICAL CHARACTERISTICS: $V_S = 1.8\text{ V}$ to $5.5\text{ V}$

At  $T_A = +25^\circ\text{C}$ ,  $R_L = 10\text{ k}\Omega$  connected to midsupply,  $V_{CM} = V_{OUT} = \text{midsupply}$ , unless otherwise noted.

**Boldface** limits apply over the specified temperature range,  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ , guaranteed by characterization and/or design.

Parameter	Symbol	Conditions		Min	Typ	Max	Unit	
INPUT CHARACTERISTICS								
Offset Voltage	V <sub>OS</sub>	NCS325	V <sub>S</sub> = +5V		14	50	μV	
		NCS2325, NCS4325	V <sub>S</sub> = +5V		14	75		
Offset Voltage Drift vs Temp	ΔV <sub>OS</sub> /ΔT	T <sub>A</sub> = −40°C to 125°C			<b>0.02</b>	<b>0.25</b>	μV/°C	
Input Bias Current	I <sub>IB</sub>				±50		pA	
Input Offset Current	I <sub>OS</sub>				±100		pA	
Common Mode Rejection Ratio	CMRR	NCS325	V <sub>SS</sub> +0.3 < V <sub>CM</sub> < V <sub>DD</sub> − 0.3, V <sub>S</sub> = 1.8 V	<b>85</b>	108		dB	
			V <sub>SS</sub> +0.3 < V <sub>CM</sub> < V <sub>DD</sub> − 0.3, V <sub>S</sub> = 5.5 V	<b>90</b>	110			
		NCS2325, NCS4325	V <sub>SS</sub> +0.3 < V <sub>CM</sub> < V <sub>DD</sub> − 0.3, V <sub>S</sub> = 5 V	<b>90</b>	110			
		V <sub>SS</sub> −0.1 < V <sub>CM</sub> < V <sub>DD</sub> + 0.1, V <sub>S</sub> = 1.8 V			80			
		V <sub>SS</sub> −0.1 < V <sub>CM</sub> < V <sub>DD</sub> + 0.1, V <sub>S</sub> = 5.5 V			92			
Input Resistance	R <sub>IN</sub>					15		GΩ
Input Capacitance	C <sub>IN</sub>	NCS325	Differential			1.8		pF
			Common Mode			3.5		pF
		NCS2325, NCS4325	Differential			4.1		pF
			Common Mode			8.0		pF

## OUTPUT CHARACTERISTICS

Output Voltage High	$V_{OH}$	Output swing within $V_{DD}$			12	100	mV
Output Voltage Low	$V_{OL}$	Output swing within $V_{SS}$			8	100	mV
Short Circuit Current	$I_{SC}$				$\pm 5$		mA
Open Loop Output Impedance	$Z_{out-OL}$	$f = 350\text{ kHz}$ , $I_O = 0\text{ mA}$ , $V_S = 1.8\text{ V}$			1.4		k $\Omega$
		$f = 350\text{ kHz}$ , $I_O = 0\text{ mA}$ , $V_S = 5.5\text{ V}$			2.7		
Capacitive Load Drive	$C_L$			See Figure			

## NOISE PERFORMANCE

Voltage Noise Density	$e_N$	$f_{IN} = 1\text{ kHz}$			100		nV / $\sqrt{\text{Hz}}$
Voltage Noise	$e_{P-P}$	$f_{IN} = 0.01\text{ Hz}$ to $1\text{ Hz}$			0.3		$\mu\text{V}_{PP}$
		$f_{IN} = 0.1\text{ Hz}$ to $10\text{ Hz}$			1		$\mu\text{V}_{PP}$
Current Noise Density	$i_N$	$f_{IN} = 10\text{ Hz}$			0.3		pA / $\sqrt{\text{Hz}}$

## DYNAMIC PERFORMANCE

Open Loop Voltage Gain	$A_{VOL}$	$R_L = 10\text{ k}\Omega$ , $V_S = 5.5\text{ V}$			114		dB
Gain Bandwidth Product	GBWP	NCS325	$C_L = 100\text{ pF}$ , $R_L = 10\text{ k}\Omega$		350		kHz
		NCS2325, NCS4325	$C_L = 100\text{ pF}$ , $R_L = 10\text{ k}\Omega$		270		
Phase Margin	$\phi_M$	$C_L = 100\text{ pF}$			60		$^\circ$
Gain Margin	$A_M$	$C_L = 100\text{ pF}$			20		dB
Slew Rate	SR	$G = +1$ , $C_L = 100\text{ pF}$ , $V_S = 1.8\text{ V}$			0.10		V/ $\mu\text{s}$
		$G = +1$ , $C_L = 100\text{ pF}$ , $V_S = 5.5\text{ V}$			0.16		

## POWER SUPPLY

Power Supply Rejection Ratio	PSRR			100	107		dB
		$T_A = -40^\circ\text{C}$ to $125^\circ\text{C}$		<b>95</b>			
Turn-on Time	$t_{ON}$	$V_S = 5\text{ V}$			100		$\mu\text{s}$
Quiescent Current	$I_Q$	No load			21	<b>35</b>	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

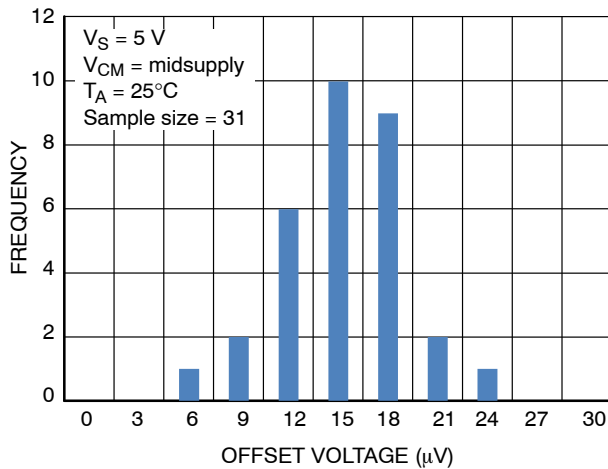


Figure 1. Offset Voltage Distribution

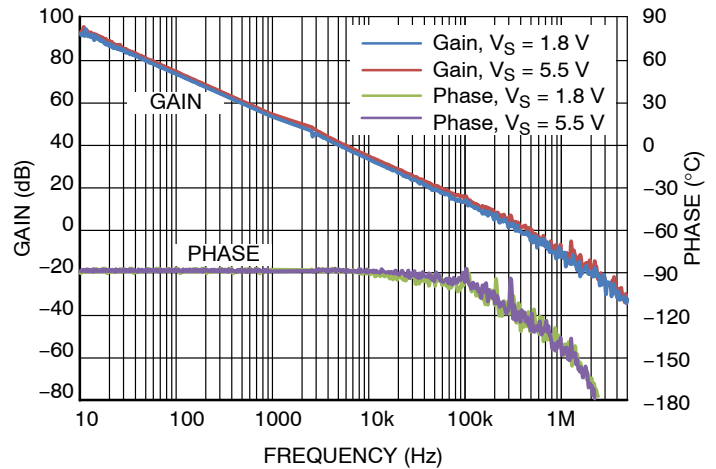


Figure 2. Gain and Phase vs. Frequency

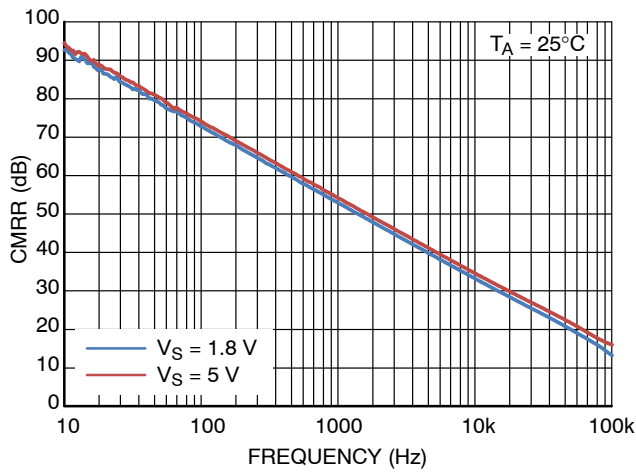


Figure 3. CMRR vs. Frequency

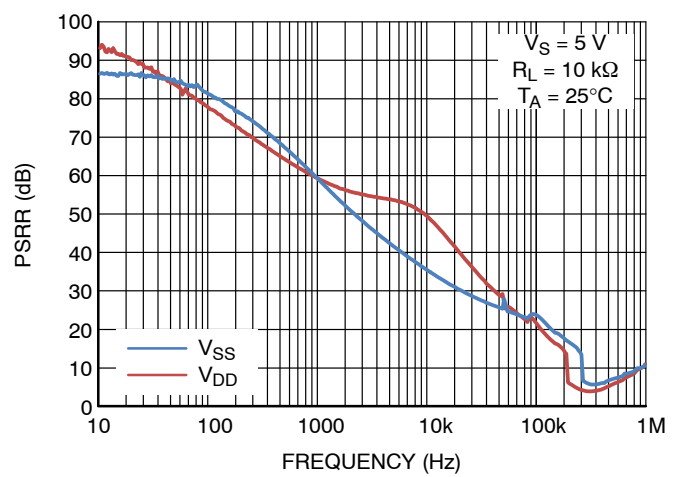


Figure 4. PSRR vs. Frequency

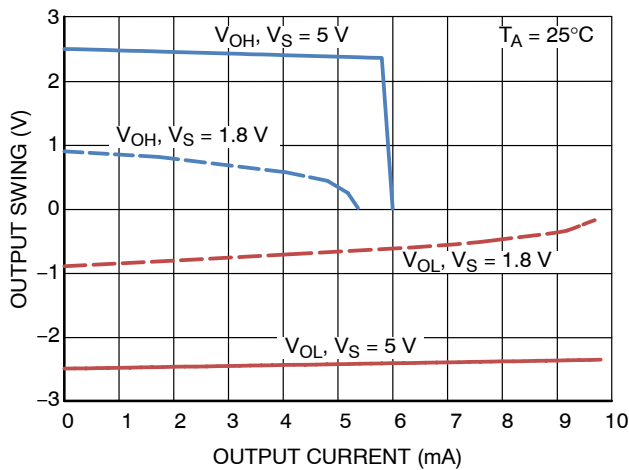


Figure 5. Output Voltage Swing vs. Output Current

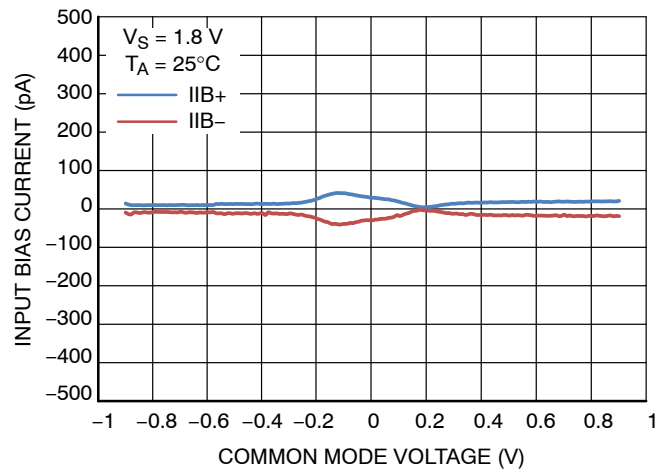


Figure 6. Input Bias Current vs. Common Mode Voltage,  $V_S = 1.8\text{ V}$

TYPICAL CHARACTERISTICS (Continued)

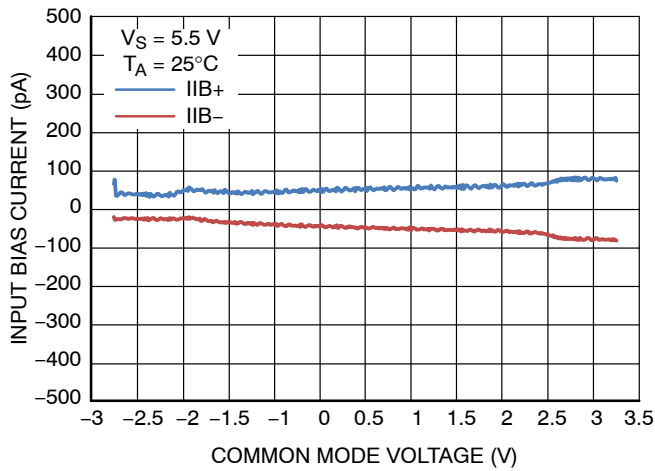


Figure 7. Input Bias Current vs. Common Mode Voltage,  $V_S = 5.5 \text{ V}$

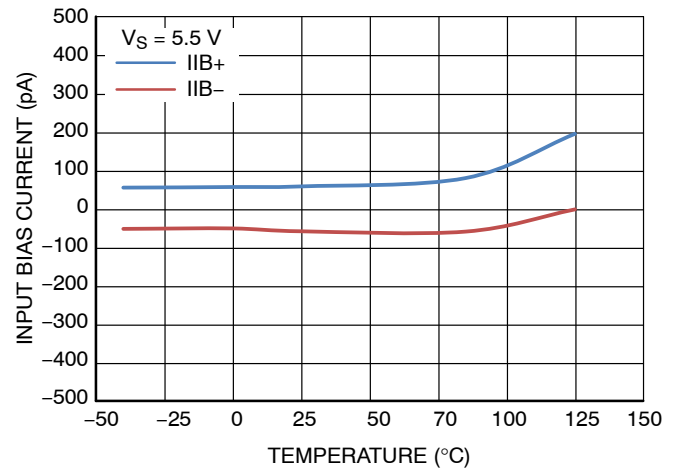


Figure 8. Input Bias Current vs. Temperature

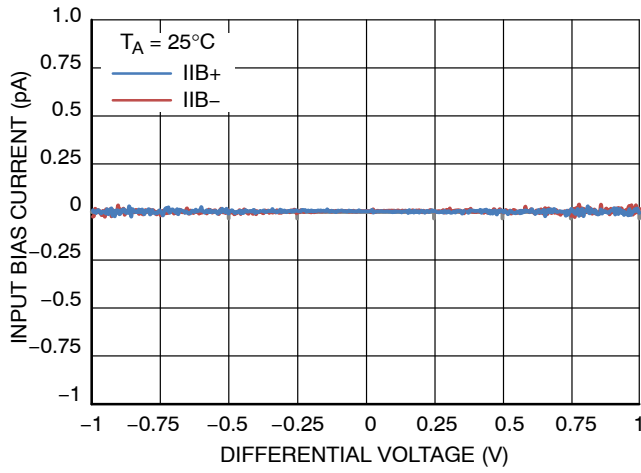


Figure 9. Input Bias Current vs. Input Differential Voltage

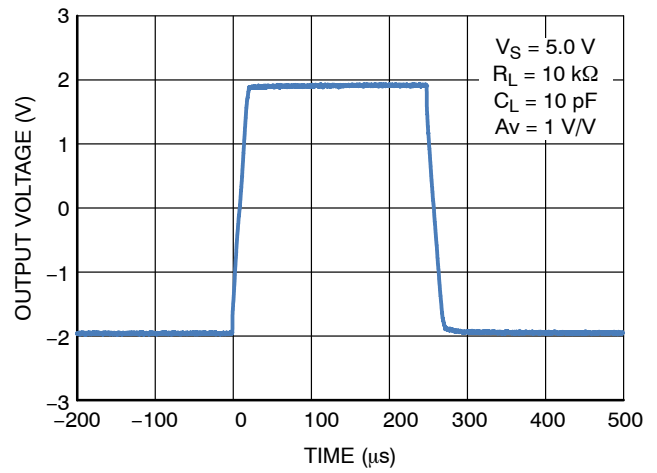


Figure 10. Large Signal Step Response

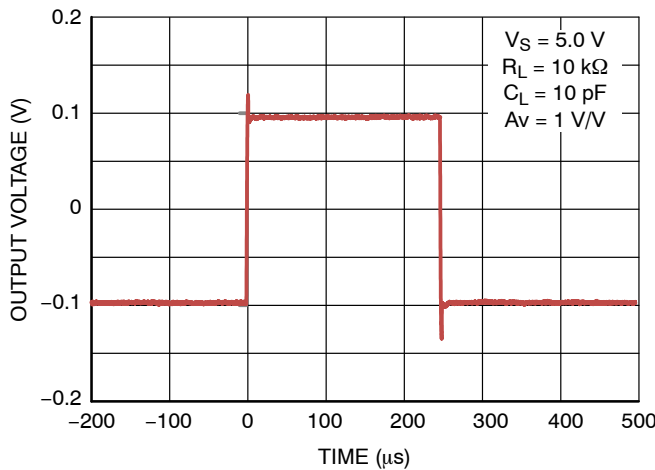


Figure 11. Small Signal Step Response

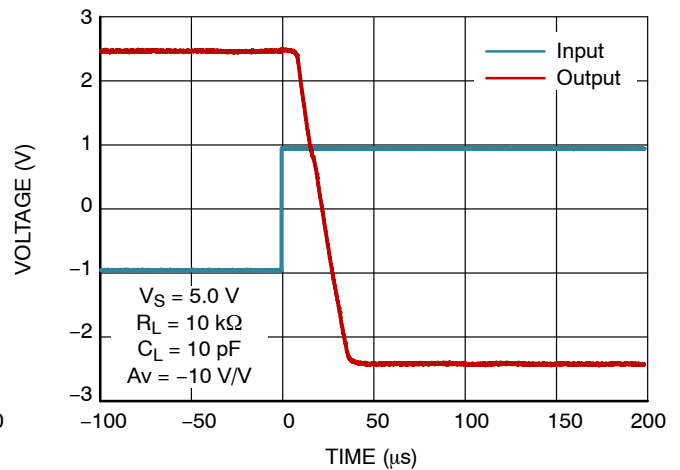


Figure 12. Positive Over Voltage Recovery

TYPICAL CHARACTERISTICS (Continued)

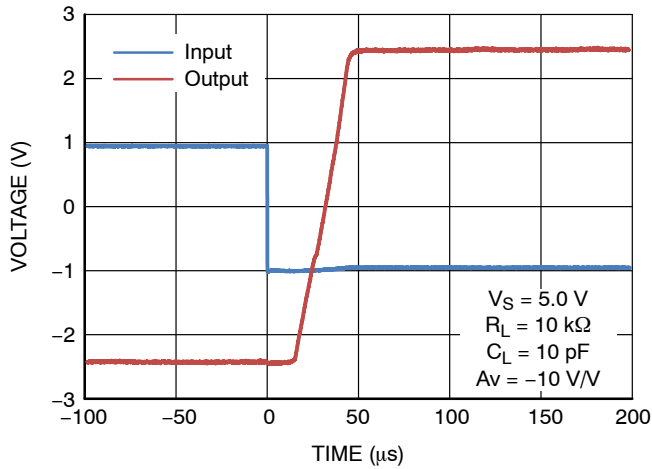


Figure 13. Negative Over Voltage Recovery

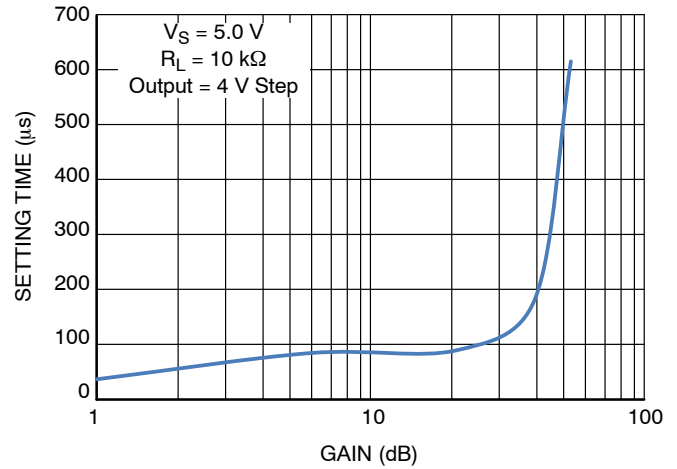


Figure 14. Setting Time vs. Closed Loop Gain

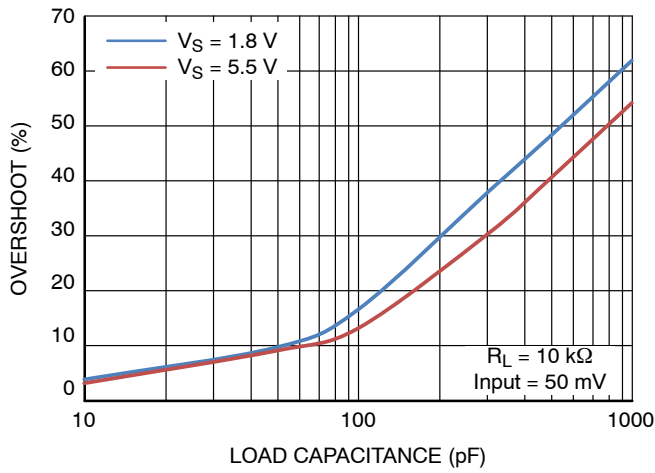


Figure 15. Small Signal Overshoot vs. Load Capacitance

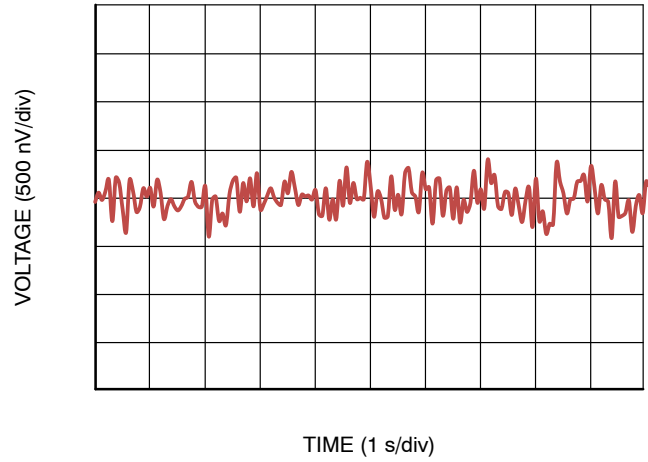


Figure 16. 0.1 Hz to 10 Hz Noise

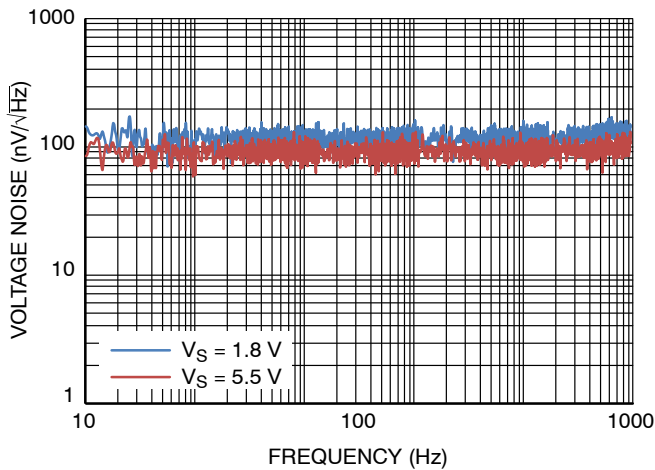


Figure 17. Voltage Noise Spectral Density vs. Frequency

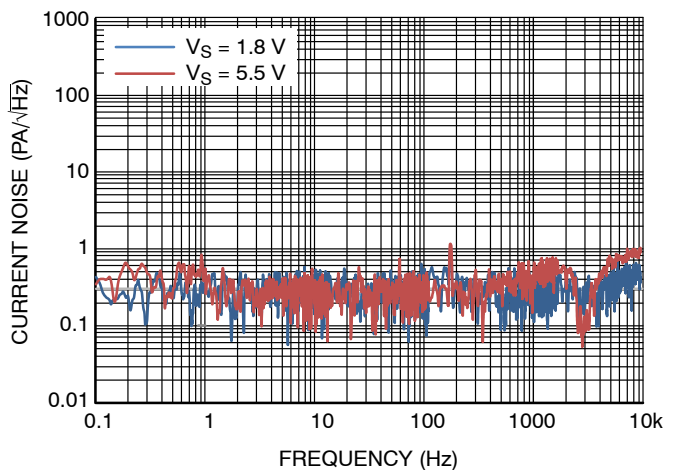


Figure 18. Current Noise Spectral Density vs. Frequency

TYPICAL CHARACTERISTICS (Continued)

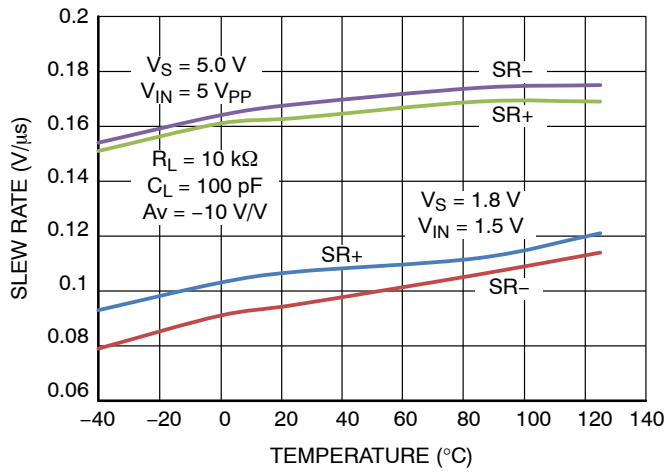


Figure 19. Slew Rate vs. Temperature

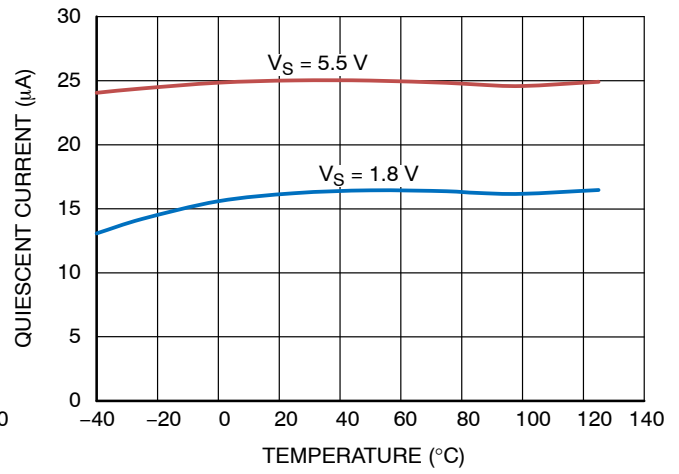


Figure 20. Quiescent Current vs. Temperature

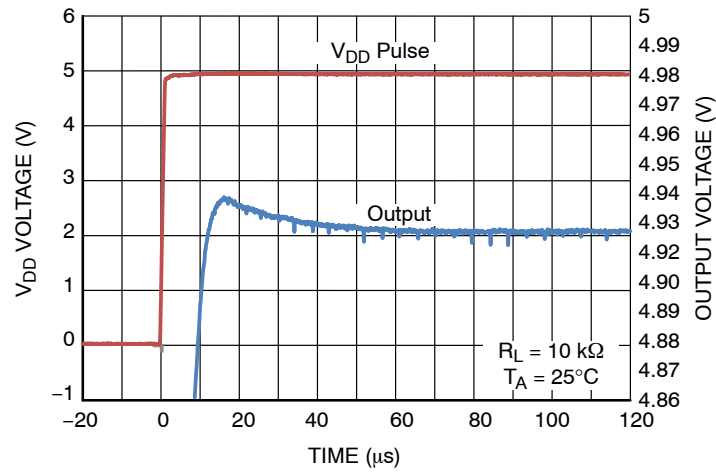


Figure 21. Turn-on Response

## APPLICATIONS INFORMATION

### INPUT VOLTAGE

The NCS325, NCS2325 and NCS4325 have rail-to-rail common mode input voltage range. Diodes between the inputs and the supply rails keep the input voltage from exceeding the rails.

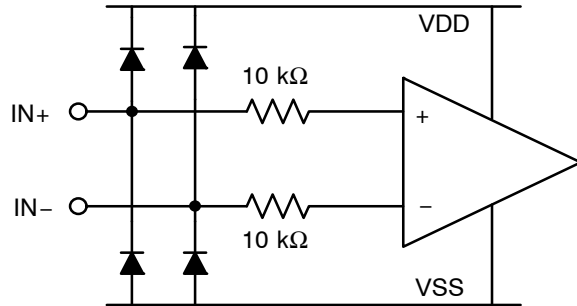


Figure 22. Equivalent Input Circuit

### EMI SUSCEPTIBILITY AND INPUT FILTERING

Op amps have varying amounts of EMI susceptibility. Semiconductor junctions can pick up and rectify EMI signals, creating an EMI-induced voltage offset at the output, adding another component to the total error. Input pins are the most sensitive to EMI. The NCS325, NCS2325 and NCS4325 integrate a low-pass filter to decrease its sensitivity to EMI.

### APPLICATION CIRCUITS

#### Low-Side Current Sensing

The goal of low-side current sensing is to detect over-current conditions or as a method of feedback control. A sense resistor is placed in series with the load to ground. Typically, the value of the sense resistor is less than 100 mΩ to reduce power loss across the resistor. The op amp amplifies the voltage drop across the sense resistor with a gain set by external resistors R1, R2, R3, and R4 (where R1 = R2, R3 = R4). Precision resistors are required for high accuracy, and the gain is set to utilize the full scale of the ADC for the highest resolution.

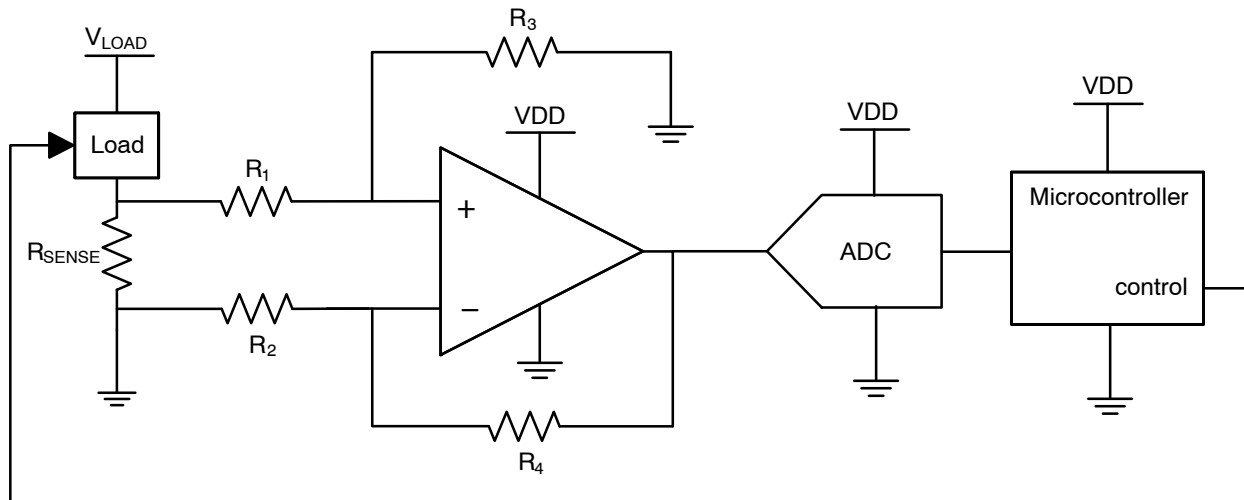


Figure 23. Low-Side Current Sensing

### Differential Amplifier for Bridged Circuits

Sensors to measure strain, pressure, and temperature are often configured in a Wheatstone bridge circuit as shown in Figure 24. In the measurement, the voltage change that is

produced is relatively small and needs to be amplified before going into an ADC. Precision amplifiers are recommended in these types of applications due to their high gain, low noise, and low offset voltage.

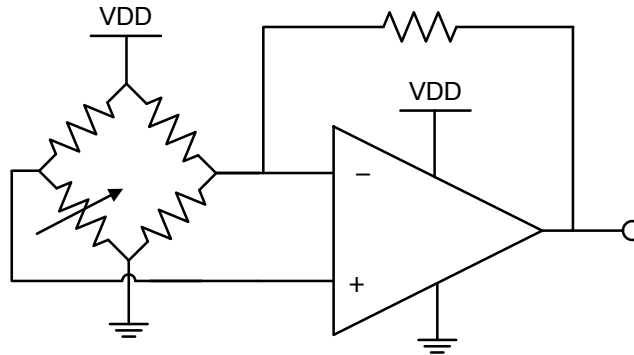


Figure 24. Bridge Circuit Amplification

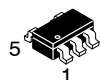
### GENERAL LAYOUT GUIDELINES

To ensure optimum device performance, it is important to follow good PCB design practices. Place 0.1  $\mu$ F decoupling capacitors as close as possible to the supply pins. Keep traces short, utilize a ground plane, choose surface-mount components, and place components as close as possible to

the device pins. These techniques will reduce susceptibility to electromagnetic interference (EMI). Thermoelectric effects can create an additional temperature dependent offset voltage at the input pins. To reduce these effects, use metals with low thermoelectric-coefficients and prevent temperature gradients from heat sources or cooling fans.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

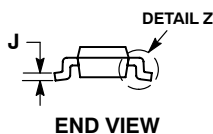
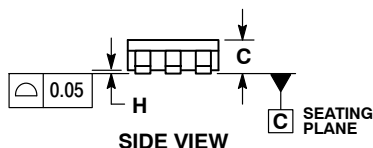
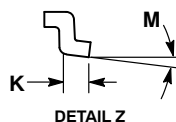
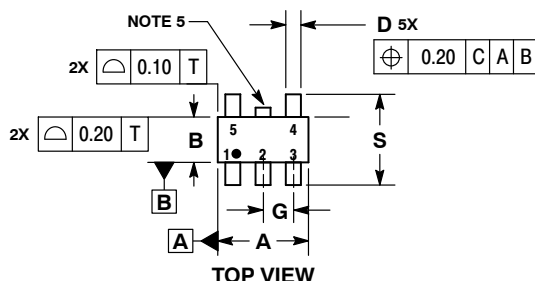
ON Semiconductor®



SCALE 2:1

## TSOP-5 CASE 483 ISSUE N

DATE 12 AUG 2020

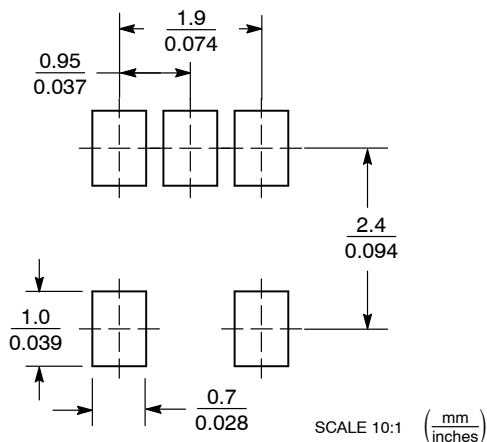


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

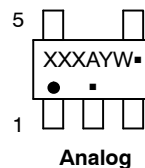
DIM	MILLIMETERS	
	MIN	MAX
A	2.85	3.15
B	1.35	1.65
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0°	10°
S	2.50	3.00

### SOLDERING FOOTPRINT\*

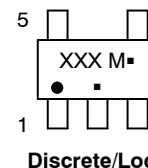


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM\*



Analog



Discrete/Logic

XXX = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ■ = Pb-Free Package

XXX = Specific Device Code  
 M = Date Code  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

DOCUMENT NUMBER: 98ARB18753C

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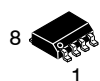
DESCRIPTION: TSOP-5

PAGE 1 OF 1

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

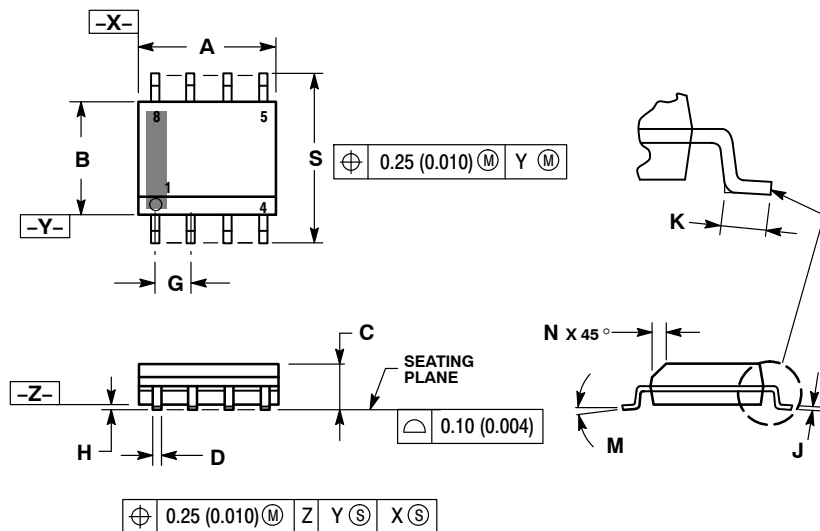
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SCALE 1:1

SOIC-8 NB  
CASE 751-07  
ISSUE AK

DATE 16 FEB 2011

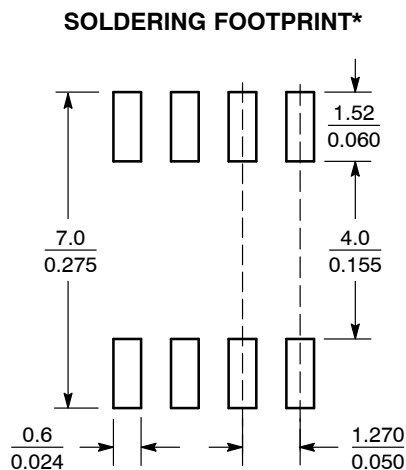


## NOTES:

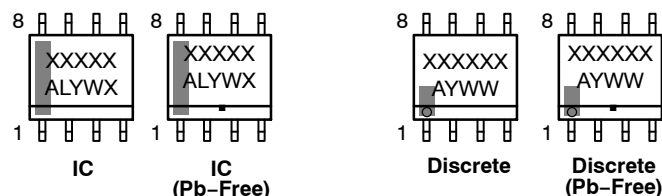
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

## GENERIC MARKING DIAGRAM\*



SCALE 6:1 (mm/inches)



XXXXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

XXXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## STYLES ON PAGE 2

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**SOIC-8 NB**  
**CASE 751-07**  
**ISSUE AK**

DATE 16 FEB 2011

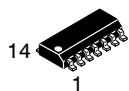
<b>STYLE 1:</b> PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	<b>STYLE 2:</b> PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1	<b>STYLE 3:</b> PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1	<b>STYLE 4:</b> PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE
<b>STYLE 5:</b> PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	<b>STYLE 6:</b> PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	<b>STYLE 7:</b> PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	<b>STYLE 8:</b> PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1
<b>STYLE 9:</b> PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	<b>STYLE 10:</b> PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	<b>STYLE 11:</b> PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	<b>STYLE 12:</b> PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
<b>STYLE 13:</b> PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	<b>STYLE 14:</b> PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	<b>STYLE 15:</b> PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	<b>STYLE 16:</b> PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
<b>STYLE 17:</b> PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	<b>STYLE 18:</b> PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE	<b>STYLE 19:</b> PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1	<b>STYLE 20:</b> PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
<b>STYLE 21:</b> PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6	<b>STYLE 22:</b> PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND	<b>STYLE 23:</b> PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT	<b>STYLE 24:</b> PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE
<b>STYLE 25:</b> PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	<b>STYLE 26:</b> PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC	<b>STYLE 27:</b> PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	<b>STYLE 28:</b> PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
<b>STYLE 29:</b> PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	<b>STYLE 30:</b> PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

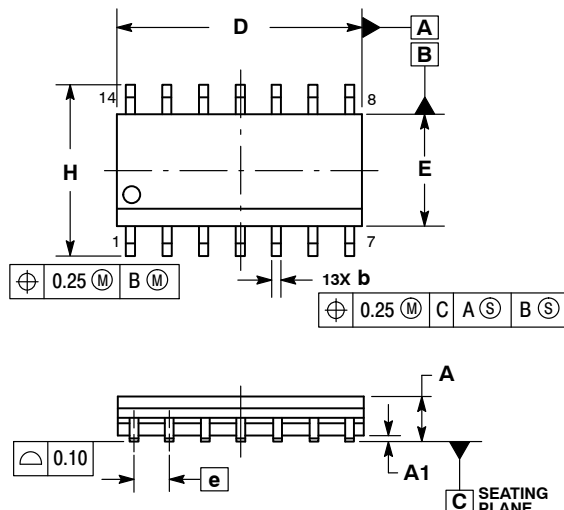
ON Semiconductor®



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

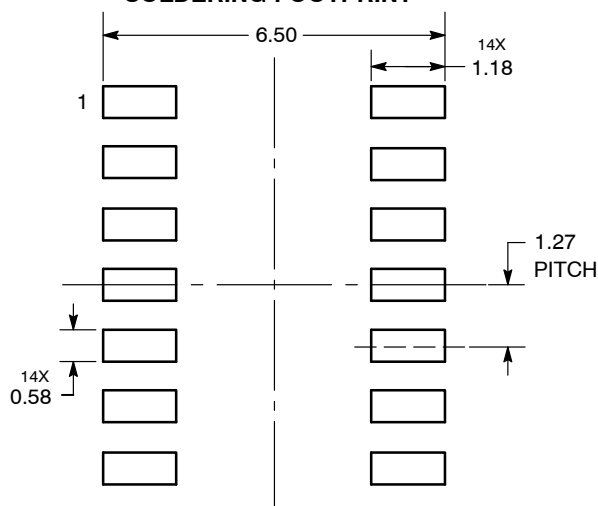


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

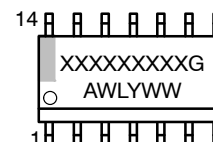
## SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## GENERIC MARKING DIAGRAM\*



\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

**DATE 03 FEB 2016**

**STYLE 1:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. NO CONNECTION  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

**STYLE 2:**  
CANCELLED

**STYLE 3:**  
PIN 1. NO CONNECTION  
2. ANODE  
3. ANODE  
4. NO CONNECTION  
5. ANODE  
6. NO CONNECTION  
7. ANODE  
8. ANODE  
9. ANODE  
10. NO CONNECTION  
11. ANODE  
12. ANODE  
13. NO CONNECTION  
14. COMMON CATHODE

**STYLE 4:**  
PIN 1. NO CONNECTION  
2. CATHODE  
3. CATHODE  
4. NO CONNECTION  
5. CATHODE  
6. NO CONNECTION  
7. CATHODE  
8. CATHODE  
9. CATHODE  
10. NO CONNECTION  
11. CATHODE  
12. CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

**STYLE 5:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. COMMON ANODE  
8. COMMON CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

**STYLE 6:**  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE  
7. CATHODE  
8. ANODE  
9. ANODE  
10. ANODE  
11. ANODE  
12. ANODE  
13. ANODE  
14. ANODE

**STYLE 7:**  
PIN 1. ANODE/CATHODE  
2. COMMON ANODE  
3. COMMON CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. COMMON CATHODE  
12. COMMON ANODE  
13. ANODE/CATHODE  
14. ANODE/CATHODE


**STYLE 8:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. COMMON ANODE  
8. COMMON ANODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. NO CONNECTION  
12. ANODE/CATHODE  
13. ANODE/CATHODE  
14. COMMON CATHODE

**DOCUMENT NUMBER:** 98ASB42565B

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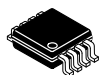
**DESCRIPTION:** SOIC-14 NB

**PAGE 2 OF 2**

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

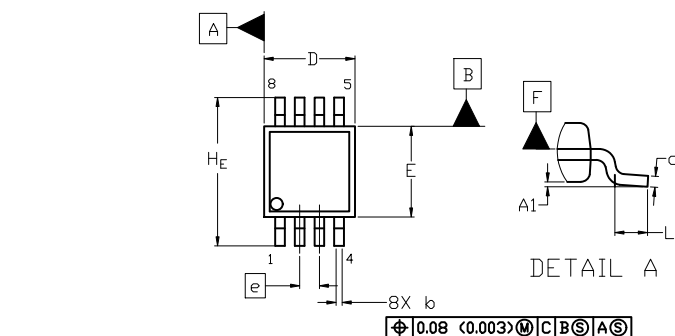
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SCALE 2:1

## Micro8 CASE 846A-02 ISSUE K

DATE 16 JUL 2020

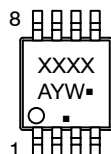


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS *D* AND *E* DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION *E* DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS *D* AND *E* ARE DETERMINED AT DATUM *F*.
5. DATUMS *A* AND *B* ARE TO BE DETERMINED AT DATUM *F*.
6. *A1* IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.10
A1	0.05	0.08	0.15
b	0.25	0.33	0.40
c	0.13	0.18	0.23
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.65 BSC		
HE	4.75	4.90	5.05
L	0.40	0.55	0.70

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

### STYLE 1:

1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

### STYLE 2:

1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

### STYLE 3:

1. N-SOURCE
2. N-GATE
3. P-SOURCE
4. P-GATE
5. P-DRAIN
6. P-DRAIN
7. N-DRAIN
8. N-DRAIN

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DESCRIPTION:	MICRO8	PAGE 1 OF 1

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